

Title (en)
LIGHT EMITTING DIODE WITH INTEGRAL HEAT DISSIPATION MEANS

Title (de)
LEUCHTDIODE MIT INTEGRIERTEM KÜHLKÖRPER

Title (fr)
DIODE ELECTROLUMINESCENTE COMPORTANT DES MOYENS INTEGRAUX DE DISSIPATION DE CHALEUR

Publication
EP 1709692 A1 20061011 (EN)

Application
EP 04706235 A 20040129

Priority
IB 2004000201 W 20040129

Abstract (en)
[origin: WO2005083804A1] Light emitting diodes are arranged with a package having an integral heat dissipation mechanism. A material having a high thermal conductivity is well coupled to a semiconductor chip providing a path for heat to be drawn away from the chip which is susceptible to overheat. In certain versions, heat dissipation mechanisms are also provided with a second terminal end which further facilitates removal of heat from the device package. The highly conductive path is formed integrally with other LED package components and cooperates therewith to provide additional support for LED functionality.

IPC 8 full level
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CPC (source: EP US)
F21V 29/763 (2015.01 - EP); **H01L 33/58** (2013.01 - EP US); **H01L 33/642** (2013.01 - EP); **F21Y 2115/10** (2016.07 - EP US); **H01L 33/60** (2013.01 - EP); **H01L 33/647** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/8592** (2013.01 - EP)

C-Set (source: EP)
H01L 2224/48091 + **H01L 2924/00014**

Citation (search report)
See references of WO 2005083804A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2005083804 A1 20050909; CA 2550308 A1 20050909; CN 1906773 A 20070131; EP 1709692 A1 20061011

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